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Product Change Notification - JAON-27DTJD589 (Printer Friendly)

Date: 07 Oct 2016
Product Category: 8-bit Microcontrollers
Notification subject: CCB 2698 Final Notice: Qualification of CuPdAu bond wire in selected products of the 200K wafer technology available in 64L QFN (9x9x0.9mm) package at MTAI assembly site.
Notification text: **PCN Status:**
Final notification

Microchip Parts Affected:

Please open the attachments found in the attachments field below labeled as PCN_#_Affected_CPN.

NOTE: For your convenience Microchip includes identical files in two formats (.pdf and .xls).

Description of Change:

Qualification of palladium coated copper with gold flash (CuPdAu) bond wire in selected products of the 200K wafer technology available in 64L QFN (9x9x0.9mm) package at MTAI assembly site.

Pre Change:

Using gold (Au) bond wire

Post Change:

Using palladium coated copper with gold flash (CuPdAu) bond wire

Pre and Post Change Summary:

	Pre Change	Post Change
Assembly Site	MTAI	MTAI
Wire material	Au wire	CuPdAu wire
Die attach material	3280	3280
Molding compound material	G700LTD	G700LTD
Lead frame material	CDA194	CDA194

Impacts to Data Sheet:

None

Change Impact:

None

Reason for Change:

To improve manufacturability by qualifying palladium coated copper with gold flash (CuPdAu) bond wire.

Change Implementation Status:

In Progress

Estimated First Ship Date:

October 30, 2016 (Date code: 1643)

NOTE: Please be advised that after the estimated first ship date customers may receive pre and post change parts.

Time Table Summary:

	October 2016			
	40	41	42	43
Workweek				
Qual Report Availability	X			
Final PCN Issue Date	X			
Estimated Implementation Date				X

Method to Identify Change:

Traceability code

Qualification Report:

Please open the attachments included with this PCN labeled as PCN_#_Qual Report.

Revision History:

October 7, 2016: Issued final notification.

The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable products.

Attachment(s):

- [PCN_JAON-27DTJD589_Qual_Report.pdf](#)
- [PCN_JAON-27DTJD589_Affected_CPN.pdf](#)
- [PCN_JAON-27DTJD589_Affected_CPN.xls](#)

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